Title (en)

STARTING MATERIAL AND PROCESS FOR PRODUCING A SINTERED CONNECTION

Title (de)

AUSGANGSWERKSTOFF UND VERFAHREN ZUR HERSTELLUNG EINER SINTERVERBINDUNG

Title (fr)

MATÉRIAU DE DÉPART ET PROCÉDÉ DE RÉALISATION D'UNE LIAISON FRITTÉE

Publication

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Application

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Abstract (en)

[origin: WO2012052191A1] The present invention relates to a starting material for producing a sintered connection. In order to avoid the formation of cracks in the joining partners in the case of fluctuating thermal loading, the starting material comprises second particles 20 in addition to metallic first particles 10, wherein the second particles 20 at least proportionately contain a particle core material which has a coefficient of thermal linear expansion a at 20°C which is less than the coefficient of thermal linear expansion a at 20°C of the metal or of the metals of the first particles in metallic form, and wherein the D50 value of the second particles 20 is greater than or equal to half the D50 value of the first particles 10 and less than or equal to two times the D50 value of the first particles 10. In addition, the present invention relates to a corresponding sintered connection 100', to an electronic circuit 70 and also to a process for forming a thermally and/or electrically conductive sintered connection.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2012052191A1

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EP 1749600 A1 20070207 - MITSUI MINING & SMELTING CO [JP]

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